

Notice of References Cited

Application/Control No.

09/763,891

Applicant(s)/Patent Under
Reexamination
UCHIDA ET AL.

Examiner

Lynette T. Umez-Eronini

Art Unit

1765

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-4968381	11-1990	Prigge et al.	156/636
	C	US-5434107	07-1995	Paranjpe	437/225
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	E	US-5770095	06-1998	Sasaki et al.	216/38
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Hayashi, Y. et al., "A New Abrasive-Free, Chemical -Mechanical-Polishing for Aluminium Metallization of ULSI Devices, International Electron Devices Meeting Technical Digest, 1992, pp. 976-978.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.